

REMARKS

By the present Amendment, the abstract has been corrected as requested by the Examiner in paragraph 2 of the Action, claim 1 has been amended to define one aspect of the invention with greater precision by including the subject matter of claim 2 and claim 2 as well as claims 5 and 6, have been cancelled without prejudice or disclaimer. The cancellation of claims 5 and 6 renders moot the rejection of claims 5 and 6 in paragraphs 4 and 5 of the Action. Since the amendment to claim 1 includes subject matter formerly claimed in claim 2 and the cancellation of claims 2, 5 and 6 substantially reduces the issues in the present application, entry of the present Amendment is in order and is respectfully requested.

The present Amendment clearly makes the present invention further distinguishable over references that the Examiner cited in the Official Action. More specifically, claim 1 has been amended so that the defined metal laminate specifies that the metal laminate has a structure in which the layer of the resin composition is formed on one surface or both surface of one or more polyimide film(s) and the metal foil layer is formed on one surface or both surface of the layer of the resin composition.

To obtain a further understanding of the presently claimed invention and an appreciation of the advantages which may be obtained therefrom, the Examiner's attention is respectfully directed to the characteristics of "solder heat resistance", particularly as described in the paragraph bridging pages 24 and 25 of application. As provided therein, "solder heat resistance" has no direct relationship with other properties such as heat resistance (heat-decomposition temperature), glass transition and softening points. The present invention can provide superior "solder

heat resistance" as shown in Table 2 on page 35 and therefore those of ordinary skill in the art would clearly not be led to an appreciation of this significant advantage of the present invention based on only fair teachings of other properties.

Before inspecting the combination of prior art, applicants respectfully note that some "suggestion or motivation" to make the proposed combination must be present and must be found in the prior art and not based on applicant's disclosure in order to establish a *prima facie* case of obviousness (*In re Vaeck*, 947 F.2d 488, 20 USPQ2d 1438 (Fed.Cir.1991)).

Yamaya et al., U.S. Patent No. 4,987,207, discloses resin compositions containing polyimide and bismaleimide but fails to teach the compositions applied to metal foils or polyimide as the Examiner noted. More specifically, there is no teaching or suggestion that such resin compositions might be available for the adhesive layer of a polyimide/metal laminate which requires specific characteristics such as excellent low-temperature adhesiveness, strong adhesiveness without voids and high-temperature processing, resistance to swelling and "solder heat resistance" which are required in the packaging process and "repairing" process (see the paragraph bridging pages 2 and 3 of the specification).

Matsuura et al., U.S. Patent No. 5,508,357, discloses an invention relating to "novel polyimides" which have solubility in organic solvents and other characteristics (col. 1, lines 12-20). One of the disclosed utilities of the polyimide is with a polymaleimide in order to provide an adhesive or varnish that is used in the preparation of printed circuit boards or prepregs (col. 1, lines 50-56), but the emphasis in the patent is on the polyimide. In this respect, Examples 1-3 of Matsuura et al. only prepare a polyimide and it is not until Example 4 that a polymaleimide is included. Furthermore, it will be noted that **Comparative** Examples

7 and 8 use the same polymaleimide that is used in certain illustrative Examples with comparative polyimides. Thus, the emphasis of Matsuura et al. is on the polyimide, not the polymaleimide.

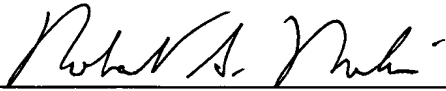
As conceded by the Examiner in the Official Action, Matsuura et al. does not teach the specific bismaleimides defined in the claims of record. In an effort to remedy this substantial deficiency, the Examiner has relied on Yamaya et al. which does not teach the specifically claimed laminate which the Examiner has again conceded. While applicants respectfully maintain that absent improper reliance on applicants' own specification, those of ordinary skill in the art would not make the hypothetical combination proposed by the Examiner, even if a proper basis for combining the patents exists, such combination would still not lead those of ordinary skill in the art to the recognition of the substantial improvements in solder heat resistance noted above which can be attained in accordance with the present invention. Accordingly, it is without question that the presently invention is patentable over the fair teachings of Yamaya et al. or Matsuura et al.

For all of the reasons set forth above, applicants respectfully submit that the claims of record overcome all of the rejections set forth in the Action and are patentable over the cited prior art. Therefore, applicants request reconsideration and allowance of the present application.

Should the Examiner wish to discuss any aspect of the present application,
she is invited to contact the undersigned attorney at the number provided below.

Respectfully submitted,

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